

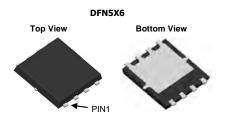
N-Channel 60 V (D-S) MOSFET

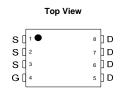
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a		
60	0.003 at $V_{GS} = 10 \text{ V}$	100		
	0.005 at $V_{GS} = 4.5 \text{ V}$	85		

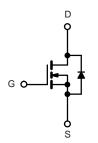
FEATURES

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:









N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Gate-Source Voltage	V_{GS}	± 20	V			
Continuous Drain Current /T 175 9C\D	T _C = 25 °C	- I _D	100			
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 100 °C		85 ^a			
Pulsed Drain Current	I _{DM}	100	A			
Continuous Source Current (Diode Conduction)	I _S	80 ^a				
Avalanche Current		I _{AS}	70			
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E _{AS}	125	mJ		
Maximum Power Dissipation	T _C = 25 °C	P _D	136	w		
Maximum Fower Dissipation	T _A = 25 °C	' D	3 ^b , 8.3 ^{b, c}]		
Operating Junction and Storage Temperature Range	•	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Mariana Landin to Ankinda	t ≤ 10 sec	R _{thJA}	15	18	°C/W	
Maximum Junction-to-Ambient ^a	Steady State		40	50		
Maximum Junction-to-Case	·	R _{thJC}	0.85	1.1		

Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- $c.\ t \leq 10\ s.$



Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit
Static			L			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1	2	3	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
		V _{DS} = 60 V, V _{GS} = 0 V			1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ
		V _{DS} = 60 V, V _{GS} = 0 V, T _J = 175 °C		250		
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	60			Α
		V _{GS} = 10 V, I _D = 20 A		0.003		
D : 0	D	V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.008		0
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C		0.010		Ω
		$V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$		0.005		
Forward Transconductance ^b	9 _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 20 \text{ A}$		60		S
Dynamic				•		
Input Capacitance	C _{iss}			2650		pF
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		470		
Reverse Transfer Capacitance	C _{rss}			225		
Total Gate Charge ^c	Q_g			47	70	
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		10		nC
Gate-Drain Charge ^c	Q_{gd}			12		
Turn-On Delay Time ^c	t _{d(on)}			10	20	
Rise Time ^c	t _r	V_{DD} = 30 V, R_L = 0.6 Ω		15	25	no
Turn-Off Delay Time ^c	t _{d(off)}	$I_D\cong 50$ A, V_{GEN} = 10 V, R_g = 2.5 Ω		35	50	ns
Fall Time ^c	t _f			20	30	
Source-Drain Diode Ratings and Cha	aracteristics (T _C = 25 °C)				
Pulsed Current	I _{SM}				60	Α
Diode Forward Voltage	V _{SD}	$I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$		1	1.5	V
Reverse Recovery Time	t _{rr}	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$		45	100	ns

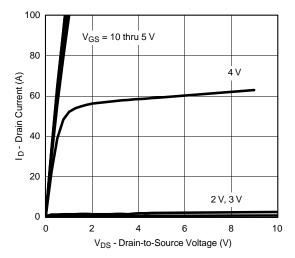
Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- c. Independent of operating temperature.

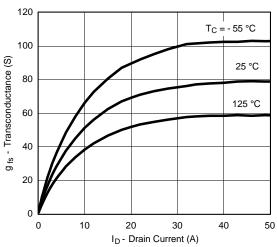
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



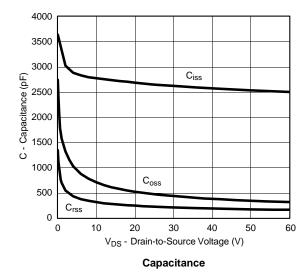
TYPICAL CHARACTERISTICS (25 °C unless noted)



Output Characteristics



Transconductance

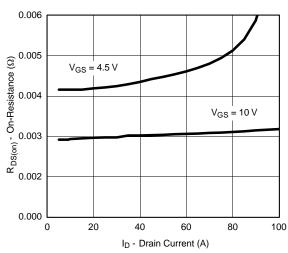


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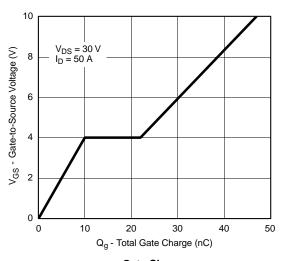
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Transfer Characteristics



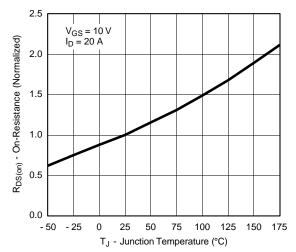
On-Resistance vs. Drain Current



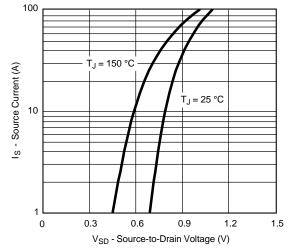
Gate Charge



TYPICAL CHARACTERISTICS (25 °C unless noted)



On-Resistance vs. Junction Temperature

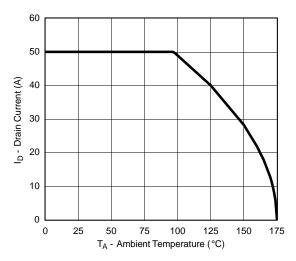


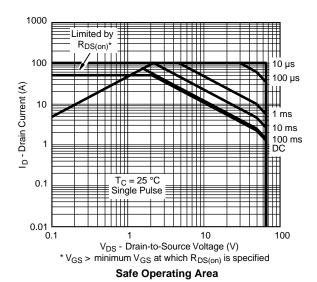
Source-Drain Diode Forward Voltage



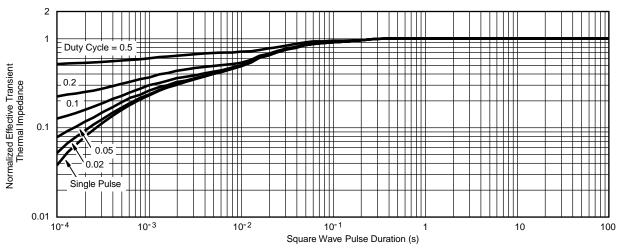
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THERMAL RATINGS





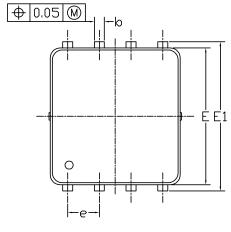
Maximum Drain Current vs. Ambient Temperature

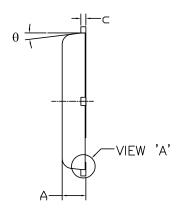


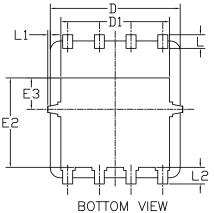
Normalized Thermal Transient Impedance, Junction-to-Case

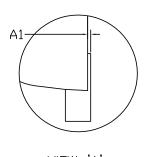


DFN5x6_8L_EP1_P PACKAGE OUTLIN



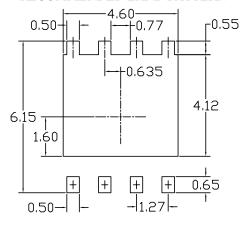






<u>VIEW 'A'</u> (SCALE 5:1)

RECOMMENDED LAND PATTERN



GVA (DOLG	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
SYMBOLS	MIN	NOM	MAX	MIN	NOM	MAX
A	0.85	0. 95	1.00	0.033	0.037	0.039
A1	0.00		0.05	0.000		0.002
b	0.30	0.40	0.50	0.012	0.016	0.020
c	0. 15	0. 20	0. 25	0.006	0.008	0.010
D	5. 10	5. 20	5. 30	0. 201	0. 205	0. 209
D1	4. 25	4. 35	4. 45	0. 167	0.171	0. 175
Е	5. 45	5. 55	5. 65	0. 215	0.219	0. 222
E1	5. 95	6.05	6. 15	0. 234	0. 238	0. 242
E2	3. 525	3.625	3. 725	0.139	0. 143	0. 147
E3	1. 175	1. 275	1. 375	0.046	0.050	0.054
e		1.27 BSC			0.050 BSC	
L	0.45	0. 55	0.65	0.018	0.022	0.026
L1	0		0. 15	0		0.006
L2		0.68 REF			0.027 REF	
θ	0°		10°	0°		10°

NOTE

- 1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS. MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
- 2. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

UNIT: mm



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